

(1.27 mm) .050"

RSM SERIES

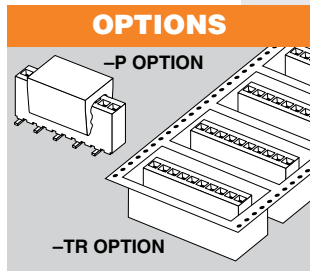
SMT MICRO SOCKET

SPECIFICATIONS

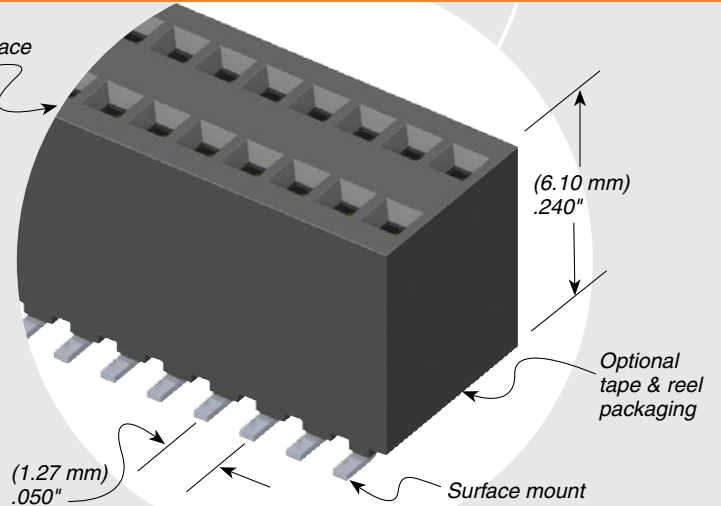
For complete specifications and recommended PCB layouts see www.samtec.com?RSM

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over
50 μ " (1.27 μ m) Ni
Current Rating (RSM/FTR):
3.1 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Lead Size Accepted:
(0.46 mm) .018" SQ
Insertion Depth:
Top Entry = (2.64 mm) .104"
to (5.84 mm) .230" with
(0.38 mm) .015" wipe, or
pass-through.
Bottom Entry = (5.49 mm)
.216" minimum
(Add board thickness for
correct post OAL)
RoHS Compliant:
Yes

Mates with:
FTR, HTMS, HDWM,
DWM, TML, ZML, TMS



Optional
pick & place
pad



PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max

RECOGNITIONS

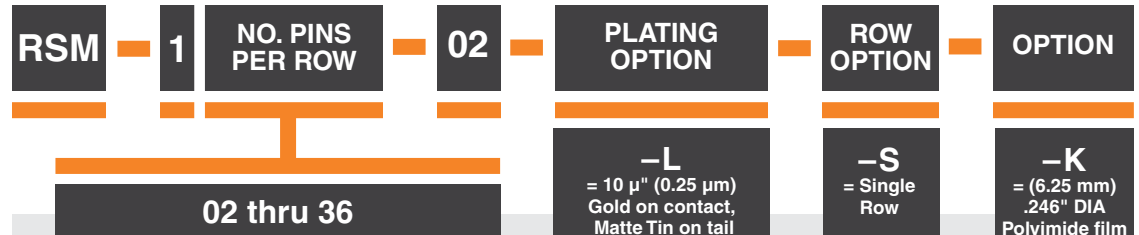
For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
 - Locking clips
- Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.



PLATING OPTION

-L
= 10 μ " (0.25 μ m)
Gold on contact,
Matte Tin on tail

ROW OPTION

-S
= Single Row

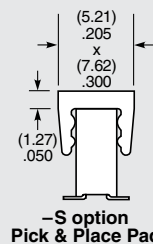
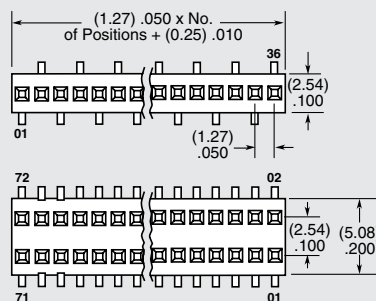
-D
= Double Row

OPTION

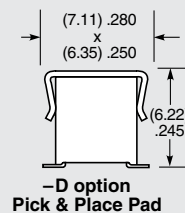
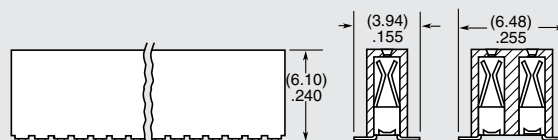
-K
= (6.25 mm)
.246" DIA
Polyimide film
Pick & Place Pad
(5 positions minimum for -D)
(7 positions minimum for -S)

-P
= Plastic
Pick & Place Pad
(-D = 5 positions minimum
-S = 6 positions minimum)

-TR
= Tape & Reel



-S option
Pick & Place Pad



-D option
Pick & Place Pad

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.